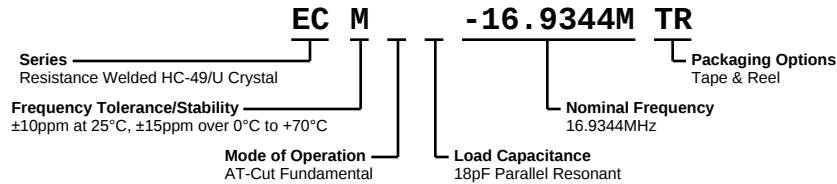


# ECM-16.9344M TR



## ELECTRICAL SPECIFICATIONS

|                               |                                                                                                             |
|-------------------------------|-------------------------------------------------------------------------------------------------------------|
| Nominal Frequency             | 16.9344MHz                                                                                                  |
| Frequency Tolerance/Stability | $\pm 10\text{ppm}$ at $25^\circ\text{C}$ , $\pm 15\text{ppm}$ over $0^\circ\text{C}$ to $+70^\circ\text{C}$ |
| Aging at $25^\circ\text{C}$   | $\pm 5\text{ppm/year}$ Maximum                                                                              |
| Load Capacitance              | 18pF Parallel Resonant                                                                                      |
| Shunt Capacitance (C0)        | 7pF Maximum                                                                                                 |
| Equivalent Series Resistance  | 25 Ohms Maximum                                                                                             |
| Mode of Operation             | AT-Cut Fundamental                                                                                          |
| Drive Level                   | 2mWatts Maximum                                                                                             |
| Storage Temperature Range     | $-40^\circ\text{C}$ to $+85^\circ\text{C}$                                                                  |
| Insulation Resistance         | 500 Megaohms Minimum at 100Vdc                                                                              |

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

|                              |                                       |
|------------------------------|---------------------------------------|
| Fine Leak Test               | MIL-STD-883, Method 1014, Condition A |
| Gross Leak Test              | MIL-STD-883, Method 1014, Condition C |
| Lead Integrity               | MIL-STD-883, Method 2004              |
| Mechanical Shock             | MIL-STD-202, Method 213, Condition C  |
| Resistance to Soldering Heat | MIL-STD-202, Method 210               |
| Resistance to Solvents       | MIL-STD-202, Method 215               |
| Solderability                | MIL-STD-883, Method 2003              |
| Temperature Cycling          | MIL-STD-883, Method 1010              |
| Vibration                    | MIL-STD-883, Method 2007, Condition A |

# ECM-16.9344M TR

MECHANICAL DIMENSIONS (all dimensions in millimeters)

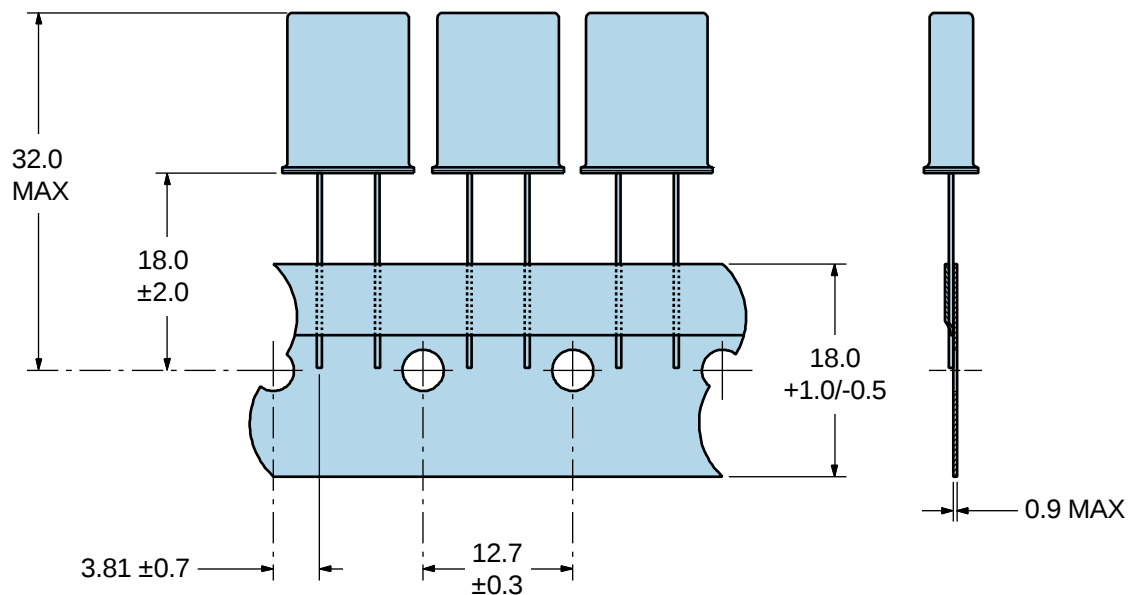


| LINE | MARKING                                                                   |
|------|---------------------------------------------------------------------------|
| 1    | <b>ECLIPTEK</b>                                                           |
| 2    | <b>E16.934M</b><br><i>E=Ecliptek Designator or<br/>Blank (No Marking)</i> |
| 3    | <b>XX</b><br><i>XX=Ecliptek Manufacturing<br/>Code</i>                    |

# ECM-16.9344M TR

## Tape & Reel Dimensions

Quantity Per Reel: 1,000 Pieces



\*Compliant to EIA 468B



## Recommended Solder Reflow Methods



### High Temperature Solder Bath (Wave Solder)

|                                   |                    |
|-----------------------------------|--------------------|
| $T_S$ MAX to $T_L$ (Ramp-up Rate) | 3°C/second Maximum |
|-----------------------------------|--------------------|

#### Preheat

|                                    |                  |
|------------------------------------|------------------|
| - Temperature Minimum ( $T_S$ MIN) | 150°C            |
| - Temperature Typical ( $T_S$ TYP) | 175°C            |
| - Temperature Maximum ( $T_S$ MAX) | 200°C            |
| - Time ( $t_s$ MIN)                | 60 - 180 Seconds |

|                                 |                    |
|---------------------------------|--------------------|
| Ramp-up Rate ( $T_L$ to $T_P$ ) | 3°C/second Maximum |
|---------------------------------|--------------------|

#### Time Maintained Above:

|                         |                  |
|-------------------------|------------------|
| - Temperature ( $T_L$ ) | 217°C            |
| - Time ( $t_L$ )        | 60 - 150 Seconds |

|                            |                                      |
|----------------------------|--------------------------------------|
| Peak Temperature ( $T_P$ ) | 260°C Maximum for 10 Seconds Maximum |
|----------------------------|--------------------------------------|

|                                         |               |
|-----------------------------------------|---------------|
| Target Peak Temperature ( $T_P$ Target) | 250°C +0/-5°C |
|-----------------------------------------|---------------|

|                                          |                 |
|------------------------------------------|-----------------|
| Time within 5°C of actual peak ( $t_p$ ) | 20 - 40 seconds |
|------------------------------------------|-----------------|

|                |                    |
|----------------|--------------------|
| Ramp-down Rate | 6°C/second Maximum |
|----------------|--------------------|

|                                   |                   |
|-----------------------------------|-------------------|
| Time 25°C to Peak Temperature (t) | 8 minutes Maximum |
|-----------------------------------|-------------------|

|                            |         |
|----------------------------|---------|
| Moisture Sensitivity Level | Level 1 |
|----------------------------|---------|

## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder)

T<sub>S</sub> MAX to T<sub>L</sub> (Ramp-up Rate) 5°C/second Maximum

#### Preheat

- Temperature Minimum (T<sub>S</sub> MIN) N/A  
 - Temperature Typical (T<sub>S</sub> TYP) 150°C  
 - Temperature Maximum (T<sub>S</sub> MAX) N/A  
 - Time (t<sub>S</sub> MIN) 30 - 60 Seconds

Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>) 5°C/second Maximum

#### Time Maintained Above:

- Temperature (T<sub>L</sub>) 150°C  
 - Time (t<sub>L</sub>) 200 Seconds Maximum

Peak Temperature (T<sub>P</sub>) 245°C Maximum

Target Peak Temperature (T<sub>P</sub> Target) 245°C Maximum 1 Time / 235°C Maximum 2 Times

Time within 5°C of actual peak (t<sub>P</sub>) 5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.